HARRIS Semiconductor

# RFH25P08, RFH25P10, RFK25P08, RFK25P10

## -25A, -100V and -80V, 0.150 Ohm, P-Channel Power MOSFETs

September 1998

### Features

- **-25A, -100V and -80V**
- **$r_{DS(ON)}$ = 0.150Ω**
- **Related Literature**
  - **TB334 "Guidelines for Soldering Surface Mount Components to PC Boards"**

### Ordering Information

| PART NUMBER | PACKAGE | BRAND |
|---|---|---|
| RFH25P08 | TO-218AC | RFH25P08 |
| RFH25P10 | TO-218AC | RFH25P10 |
| RFK25P08 | TO-204AE | RFK25P08 |
| RFK25P10 | TO-204AE | RFK25P10 |

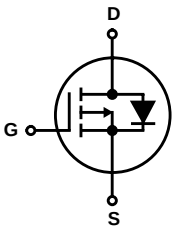
NOTE: When ordering, use the entire part number.

### Description

These are P-Channel enhancement mode silicon gate power field effect transistors designed for applications such as switching regulators, switching converters, motor drivers, relay drivers and drivers for high power bipolar switching transistors requiring high speed and low gate drive power. These types can be operated directly from integrated circuits.

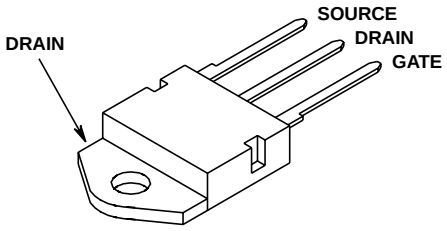
Formerly developmental type TA49230.

### Symbol

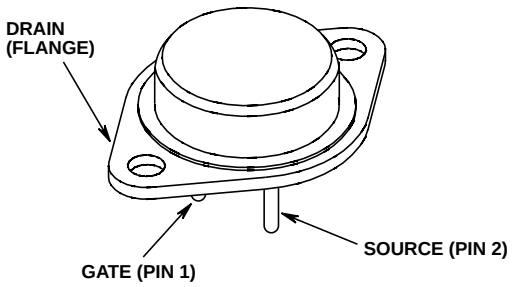



### Packaging

**JEDEC TO -218AC**




**JEDEC TO-204AE**




CAUTION: These devices are sensitive to electrostatic discharge. Users should follow proper ESD Handling Procedures.



File Number **1632.1**

## Absolute Maximum Ratings $T_C = 25^oC$, Unless Otherwise Specified

| | | RFH25P08 RFK25P08 | RFH25P10 RFK25P10 | UNITS |
|---|---|---|---|---|
| Drain to Source Voltage (Note 1) | $V_{DS}$ | -80 | -100 | V |
| Drain to Gate Voltage ($R_{GS}$ = 20kΩ) (Note 1) | $V_{DGR}$ | -80 | -100 | V |
| Continuous Drain Current | $I_D$ | -25 | -25 | A |
| Pulsed Drain Current (Note 3) | $I_{DM}$ | -60 | -60 | A |
| Gate to Source Voltage | $V_{GS}$ | ±20 | ±20 | V |
| Maximum Power Dissipation | $P_D$ | 150 | 150 | W |
| Linear Derating Factor | | 1.2 | 1.2 | W/$^o$C |
| Operating and Storage Temperature | $T_J$, $T_{STG}$ | -55 to 150 | -55 to 150 | $^o$C |
| Maximum Temperature for Soldering | | | | |
| Leads at 0.063in (1.6mm) from Case for 10s | $T_L$ | 300 | 300 | $^o$C |
| Package Body for 10s, See Techbrief 334 (for TO-218AC) | $T_{pkg}$ | 260 | 260 | $^o$C |

*CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.*

NOTE:

1. $T_J = 25^oC$ to $125^oC$.

## Electrical Specifications $T_C = 25^oC$, Unless Otherwise Specified

| PARAMETER | SYMBOL | TEST CONDITIONS | MIN | TYP | MAX | UNITS |
|---|---|---|---|---|---|---|
| Drain to Source Breakdown Voltage | $BV_{DSS}$ | $I_D$ = 250μA, $V_{GS}$ = 0V | | | | |
| RFH25P08, RFK25P08 | | | -80 | - | - | V |
| RFH25P10, RFK25P10 | | | -100 | - | - | V |
| Gate Threshold Voltage | $V_{GS(TH)}$ | $V_{GS}$ = $V_{DS}$, $I_D$ = 250μA, (Figure 8) | -2 | - | -4 | V |
| Zero Gate Voltage Drain Current | $I_{DSS}$ | $V_{DS}$ = Rated $BV_{DSS}$, $V_{GS}$ = 0 | - | - | -1 | μA |
| | | $V_{DS}$ = 0.8 x Rated $BV_{DSS}$, $V_{GS}$ = 0, $T_C = 125^oC$ | - | - | -25 | μA |
| Gate to Source Leakage Current | $I_{GSS}$ | $V_{GS}$ = ±20V, $V_{DS}$ = 0V | - | - | ±100 | nA |
| Drain to Source On Resistance (Note 2) | $r_{DS(ON)}$ | $I_D$ = 25A, $V_{GS}$ = -10V, (Figures 6, 7) | - | - | 0.150 | Ω |
| Drain to Source On Voltage (Note 2) | $V_{DS(ON)}$ | $I_D$ = -25A, $V_{GS}$ = -10V | - | - | -3.75 | V |
| Turn-On Delay Time | $t_{d(ON)}$ | $I_D \approx$ 12.5A, $V_{DS}$ = -50V, $R_{GS}$ = 50Ω, $V_{GS}$ = -10V, $R_L$ = 4.0Ω (Figures 10, 11, 12) | - | 35 | 50 | ns |
| Rise Time | $t_r$ | | - | 165 | 250 | ns |
| Turn-Off Delay Time | $t_{d(OFF)}$ | | - | 270 | 400 | ns |
| Fall Time | $t_f$ | | - | 165 | 250 | ns |
| Input Capacitance | $C_{ISS}$ | $V_{GS}$ = 0V, $V_{DS}$ = -25V, f = 1MHz (Figure 9) | - | - | 3000 | pF |
| Output Capacitance | $C_{OSS}$ | | - | - | 1500 | pF |
| Reverse-Transfer Capacitance | $C_{RSS}$ | | - | - | 600 | pF |
| Thermal Resistance Junction to Case | $R_{\theta JC}$ | RFK25P08, RFK25P10 | - | - | 0.83 | $^o$C/W |

## Source to Drain Diode Specifications

| PARAMETER | SYMBOL | TEST CONDITIONS | MIN | TYP | MAX | UNITS |
|---|---|---|---|---|---|---|
| Source to Drain Diode Voltage (Note 2) | $V_{SD}$ | $I_{SD}$ = -12.5A | - | - | -1.4 | V |
| Diode Reverse Recovery Time | $t_{rr}$ | $I_{SD}$ = -4A, $dI_{SD}/dt$ = 100A/μs | - | 300 | - | ns |

NOTES:

2. Pulse test: pulse width ≤ 300μs, duty cycle ≤ 2%.
3. Repetitive rating: pulse width limited by maximum junction temperature.

## Typical Performance Curves Unless Otherwise Specified

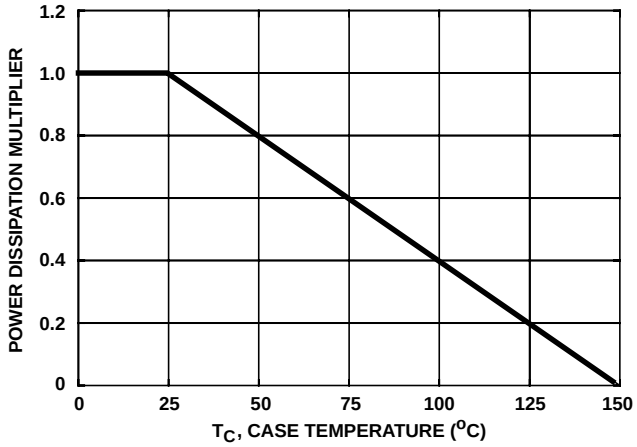



FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

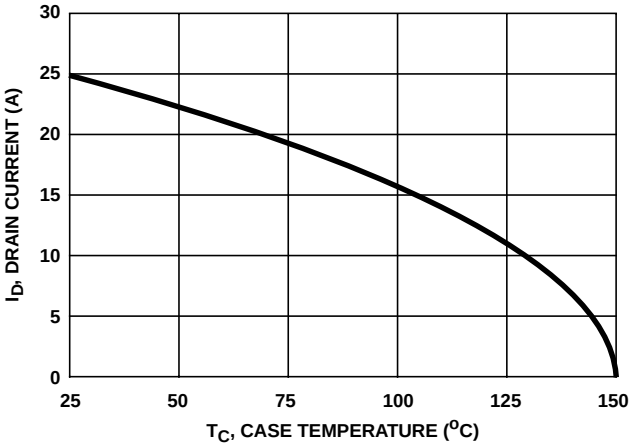



FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

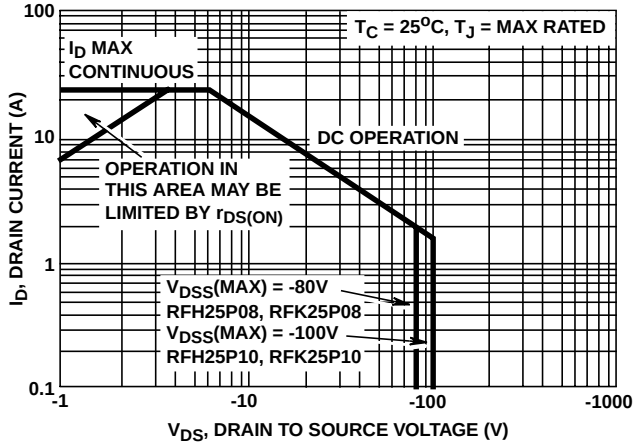



FIGURE 3. FORWARD BIAS SAFE OPERATING AREA

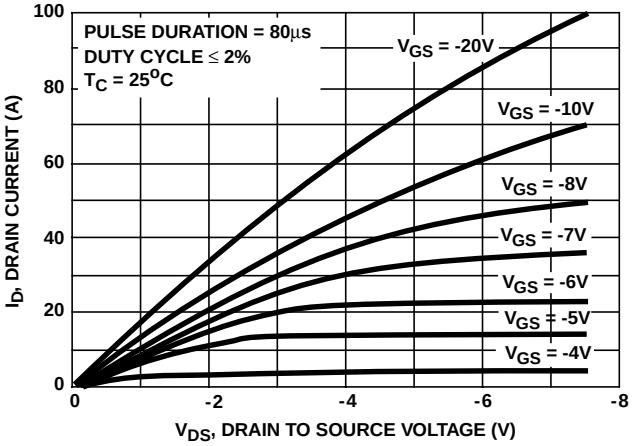



FIGURE 4. SATURATION CHARACTERISTICS

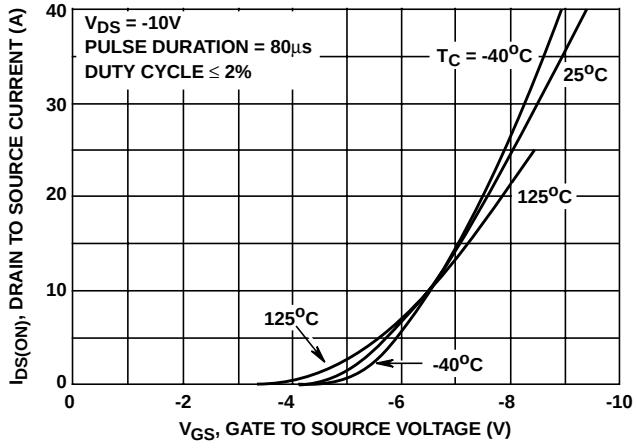



FIGURE 5. TRANSFER CHARACTERISTICS

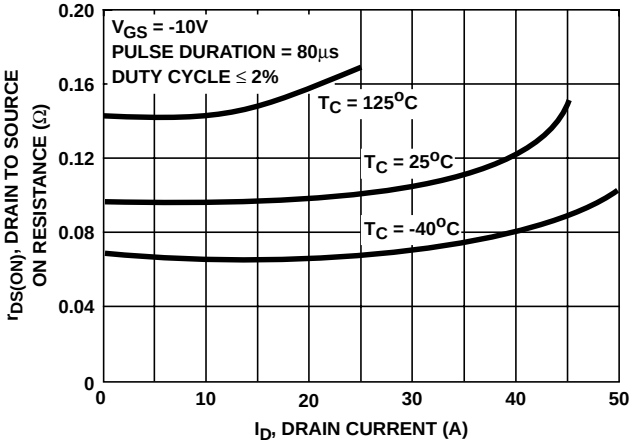



FIGURE 6. DRAIN TO SOURCE ON RESISTANCE vs DRAIN CURRENT

## Typical Performance Curves Unless Otherwise Specified **(Continued)**

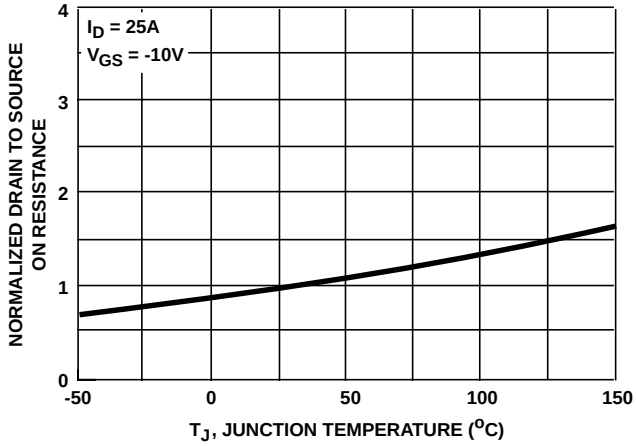



**FIGURE 7. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE**

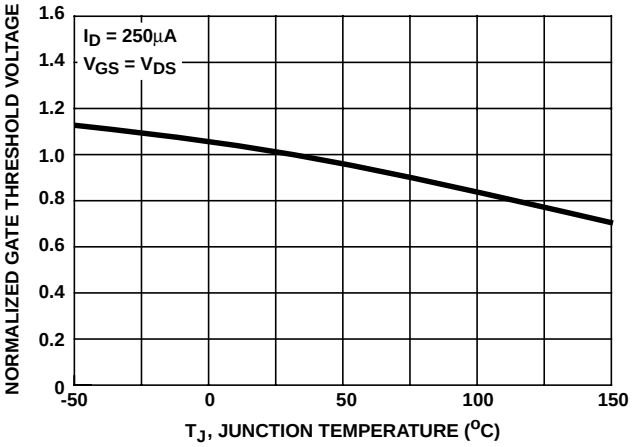



**FIGURE 8. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE**

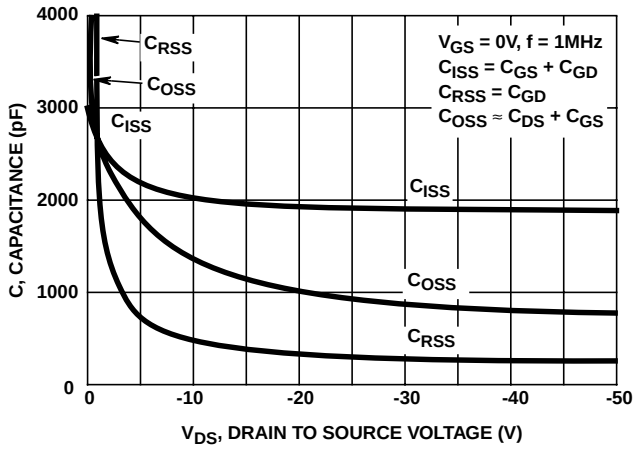
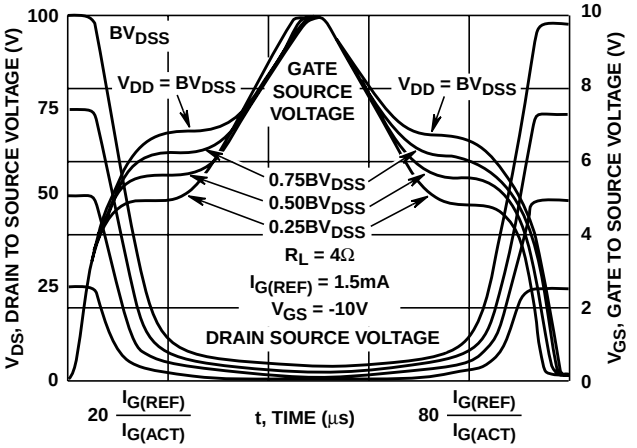



**FIGURE 9. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE**




NOTE: Refer to Harris Application Notes AN7254 and AN7260.

**FIGURE 10. NORMALIZED SWITCHING WAVEFORMS FOR CONSTANT GATE CURRENT**

## Test Circuits and Waveforms

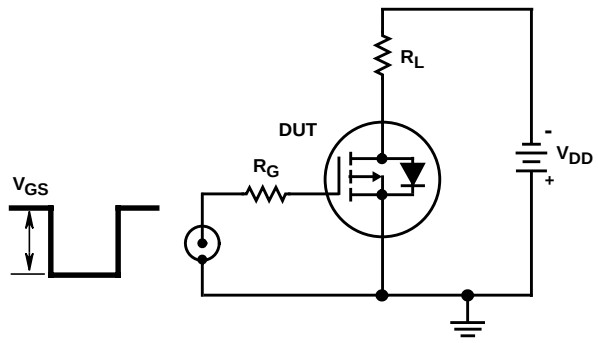



**FIGURE 11. SWITCHING TIME TEST CIRCUIT**

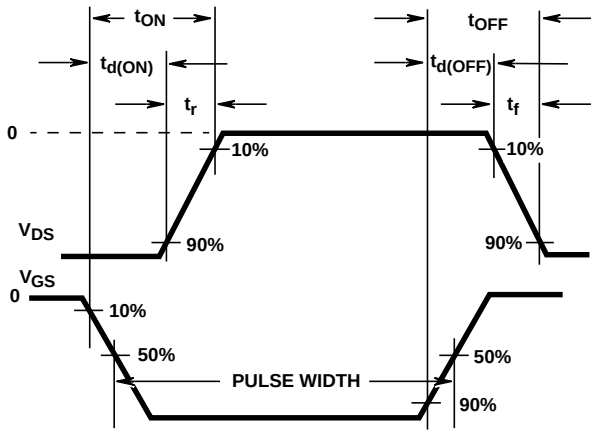



**FIGURE 12. RESISTIVE SWITCHING WAVEFORMS**